

Average Weight: 18.83g

| Component | Substance Description | CAS Number or Description | Percentage of Component | Use in Product | Component Weight/ Substance Weight (grams) | Component Percent of Total |
|-------------------------------|----------------------------|---------------------------|-------------------------|----------------|--|----------------------------|
| Silicon Die | | | | | 1.0390 | 5.52 |
| | Silicon | 7440-21-3 | 100.00 | | 1.0390 | |
| Solder Bump | | | | | 0.05127 | 0.27 |
| | Tin | 7440-31-5 | 63.00 | | 0.03229934 | |
| | Lead | 7439-92-1 | 37.00 | | 0.01896946 | |
| Underfill | | | | | 0.0740 | 0.40 |
| | Epoxy Resin A | 9003-36-5 | 20.00 | | 0.014800 | |
| | Epoxy Resin B | 25068-38-6 | 3.00 | | 0.002220 | |
| | Silica | 60676-86-0 | 70.00 | | 0.051800 | |
| | Hardener | 19900-65-3 | 7.00 | | 0.005180 | |
| Heat Spreader | | | | | 9.0000 | 47.79 |
| | Copper | 7440-50-8 | 99.90 | | 8.99100 | |
| | Nickel | 7440-02-0 | 0.10 | | 0.00900 | |
| Heat Spreader Adhesive | | | | | 0.1500 | 0.79 |
| | Organopolysiloxane mixture | N/A | 100.00 | | 0.1500 | |
| Substrate | | | | | 7.250 | 38.50 |
| | Copper | 7440-50-8 | 47.15 | Metal layer | 3.41837500 | |
| | Nickel | 7440-02-0 | 0.53 | Metal layer | 0.03842500 | |
| | Gold | 7440-57-5 | 0.12 | Metal layer | 0.00870000 | |
| | Halogen fire retardant | N/A | 5.25 | | 0.38062500 | |
| | Glass fiber | N/A | 10.30 | | 0.74675000 | |
| | BT (core) | N/A | 28.00 | | 2.03000000 | |
| | Solder mask | N/A | 8.65 | | 0.62712500 | |
| Solder Balls | | | | | 1.26725 | 6.73 |
| | Tin | 7440-31-5 | 95.50 | | 1.21022375 | |
| | Silver | 7440-22-4 | 4.00 | | 0.05069000 | |
| | Copper | 7440-50-8 | 0.50 | | 0.00633625 | |
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Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|---------|---------|---|
| 3/14/06 | 1.0 | Initial Xilinx release. |
| 6/06/06 | 1.1 | 100% Material Declaration. |
| 6/19/06 | 1.2 | Updated to include Heat Spreader Adhesive data. |
| 9/22/06 | 1.3 | Updated component descriptions and weights. |
| 7/20/10 | 1.4 | Updated Heat Spreader substance description. |

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